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Abstract of the Disclosure

A composition and method which substantially enhances the wetting of an electrolyte solution to a surface in the electrochemical plating of a metal such as copper on the surface. The composition is an organic mixture which includes an organic acid, such as citric acid or acetic acid, and a low molecular weight ionic polymer such as an alcohol, an amine or alkyphenol alkoxylate. The method includes suspending the composition as a layer in the solution and passing the surface through the composition suspension layer to define a wetting layer on the surface. Consequently, metal electroplated onto the surface is substantially devoid of pits or other structural defects.